

General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity



Applications

- PC power
- LED lighting
- Telecom power
- Server power
- EV Charger
- Solar/UPS

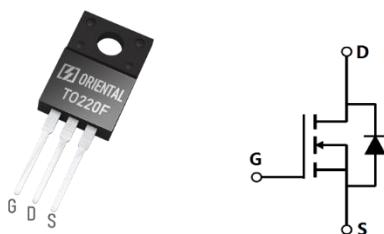
Key Performance Parameters

| Parameter | Value | Unit |
|-----------------------------------|-------|-----------|
| V_{DS} | 550 | V |
| I_D , pulse | 120 | A |
| $R_{DS(ON)}$, max @ $V_{GS}=10V$ | 92 | $m\Omega$ |
| Q_g | 38.6 | nC |

Marking Information

| Product Name | Package | Marking |
|--------------|---------|------------|
| OSG55R092FF | TO220F | OSG55R092F |

Package & Pin Information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Value | Unit |
|---|----------------------|------------|------------------|
| Drain-source voltage | V_{DS} | 550 | V |
| Gate-source voltage | V_{GS} | ± 30 | V |
| Continuous drain current ¹⁾ , $T_C=25\text{ }^\circ\text{C}$ | I_D | 40 | A |
| Continuous drain current ¹⁾ , $T_C=100\text{ }^\circ\text{C}$ | | 25 | |
| Pulsed drain current ²⁾ , $T_C=25\text{ }^\circ\text{C}$ | $I_{D,\text{pulse}}$ | 120 | A |
| Continuous diode forward current ¹⁾ , $T_C=25\text{ }^\circ\text{C}$ | I_S | 40 | A |
| Diode pulsed current ²⁾ , $T_C=25\text{ }^\circ\text{C}$ | $I_{S,\text{pulse}}$ | 120 | A |
| Power dissipation ³⁾ , $T_C=25\text{ }^\circ\text{C}$ | P_D | 34 | W |
| Single pulsed avalanche energy ⁴⁾ | E_{AS} | 770 | mJ |
| MOSFET dv/dt ruggedness, $V_{DS}=0\ldots 480\text{ V}$ | dv/dt | 50 | V/ns |
| Reverse diode dv/dt, $V_{DS}=0\ldots 480\text{ V}$, $I_{SD}\leq I_D$ | dv/dt | 15 | V/ns |
| Operation and storage temperature | T_{stg}, T_j | -55 to 150 | $^\circ\text{C}$ |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--------------------------------------|-----------------|-------|--------------------|
| Thermal resistance, junction-case | $R_{\theta JC}$ | 3.7 | $^\circ\text{C/W}$ |
| Thermal resistance, junction-ambient | $R_{\theta JA}$ | 62.5 | $^\circ\text{C/W}$ |

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|----------------------------------|---------------------|------|-------|-------|---------------|--|
| Drain-source breakdown voltage | BV_{DSS} | 550 | | | V | $V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$ |
| Gate threshold voltage | $V_{GS(\text{th})}$ | 2.9 | | 3.9 | V | $V_{DS}=V_{GS}$, $I_D=1\text{ mA}$ |
| Drain-source on-state resistance | $R_{DS(\text{ON})}$ | | 0.078 | 0.092 | Ω | $V_{GS}=10\text{ V}$, $I_D=20\text{ A}$ |
| | | | 0.183 | | | $V_{GS}=10\text{ V}$, $I_D=20\text{ A}$, $T_j=150\text{ }^\circ\text{C}$ |
| Gate-source leakage current | I_{GS} | | | 100 | nA | $V_{GS}=30\text{ V}$ |
| | | | | -100 | | $V_{GS}=-30\text{ V}$ |
| Drain-source leakage current | I_{DS} | | | 1 | μA | $V_{DS}=550\text{ V}$, $V_{GS}=0\text{ V}$ |

Dynamic Characteristics

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|------------------------------|---------------------|------|--------|------|------|---|
| Input capacitance | C _{iss} | | 2425.5 | | pF | V _{GS} =0 V, V _{DS} =50 V, f=100 kHz |
| Output capacitance | C _{oss} | | 244.3 | | pF | |
| Reverse transfer capacitance | C _{rss} | | 10.3 | | pF | |
| Turn-on delay time | t _{d(on)} | | 53.7 | | ns | V _{GS} =10 V, V _{DS} =400 V, R _G =2 Ω, I _D =20 A |
| Rise time | t _r | | 79.3 | | ns | |
| Turn-off delay time | t _{d(off)} | | 122.9 | | ns | |
| Fall time | t _f | | 59.1 | | ns | |

Gate Charge Characteristics

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|----------------------|----------------------|------|------|------|------|---|
| Total gate charge | Q _g | | 38.6 | | nC | V _{GS} =10 V, V _{DS} =400 V, I _D =20 A |
| Gate-source charge | Q _{gs} | | 9 | | nC | |
| Gate-drain charge | Q _{gd} | | 15.2 | | nC | |
| Gate plateau voltage | V _{plateau} | | 5.9 | | V | |

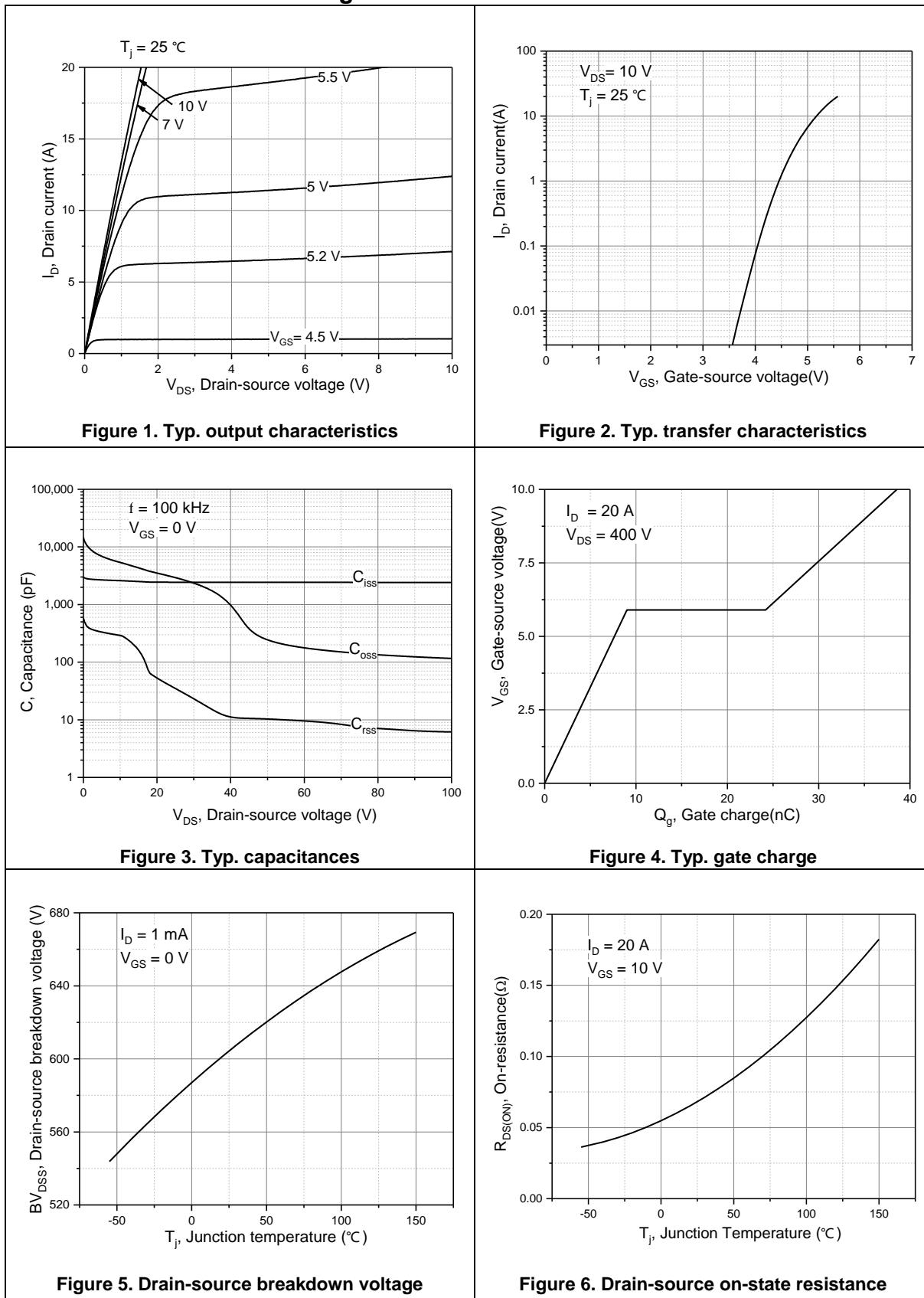
Body Diode Characteristics

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|-------------------------------|------------------|------|------|------|------|---|
| Diode forward voltage | V _{SD} | | | 1.4 | V | I _S =40 A, V _{GS} =0 V |
| Reverse recovery time | t _{rr} | | 339 | | ns | |
| Reverse recovery charge | Q _{rr} | | 4.9 | | μC | |
| Peak reverse recovery current | I _{rrm} | | 27.9 | | A | |

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) V_{DD}=100 V, V_{GS}=10 V, L=10 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams



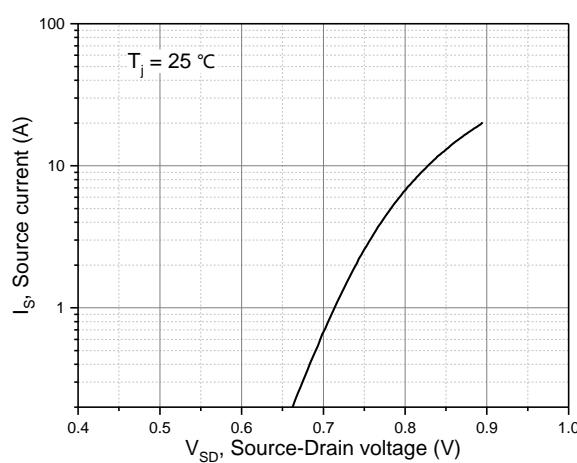


Figure 7. Forward characteristic of body diode

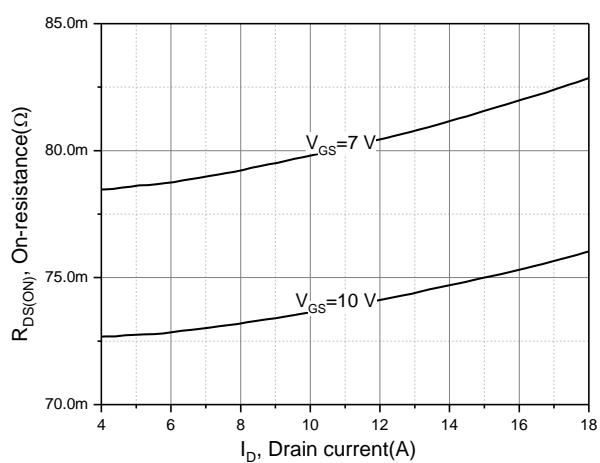


Figure 8. Drain-source on-state resistance

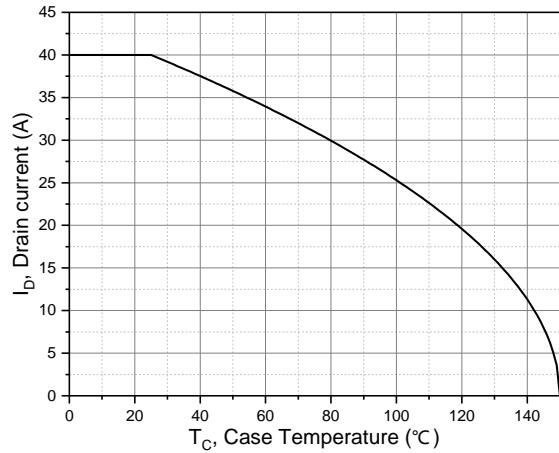


Figure 9. Drain current

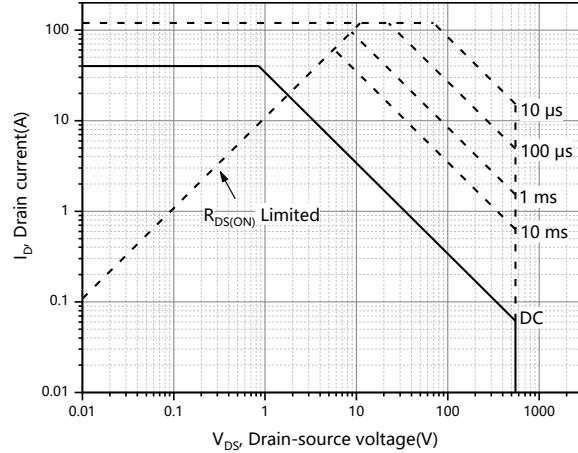


Figure 10. Safe operation area T_C=25 °C

Test circuits and waveforms

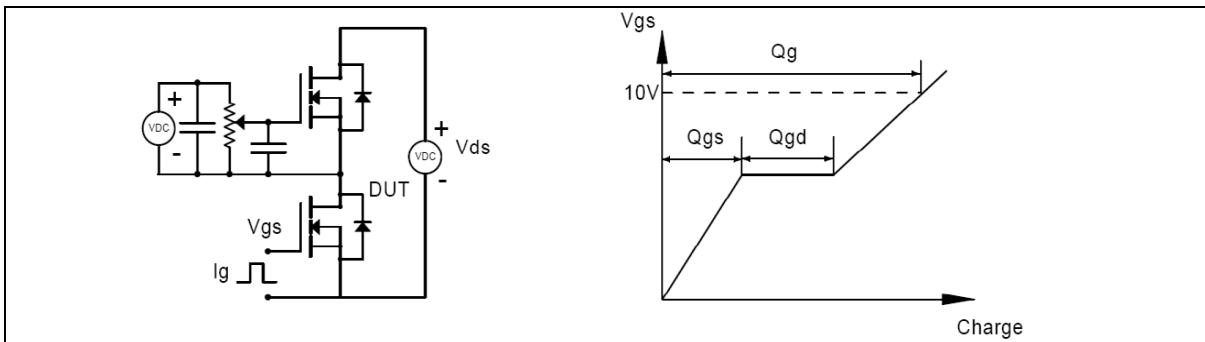


Figure 1. Gate charge test circuit & waveforms

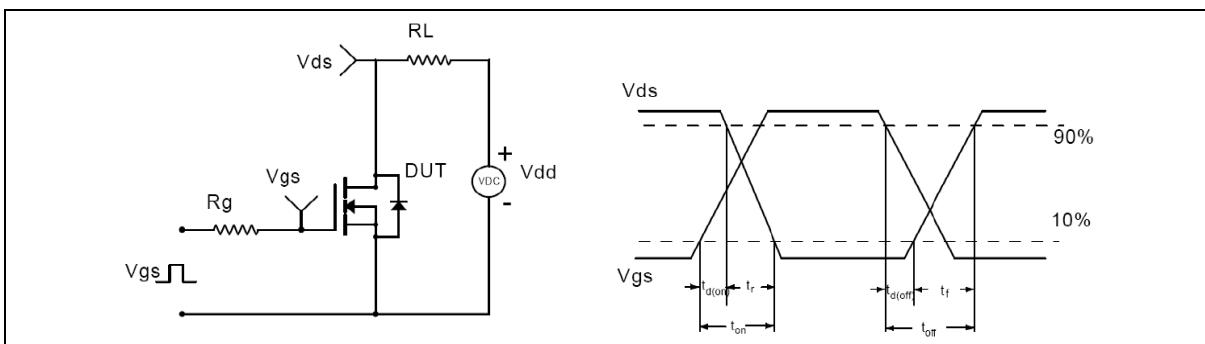


Figure 2. Switching time test circuit & waveforms

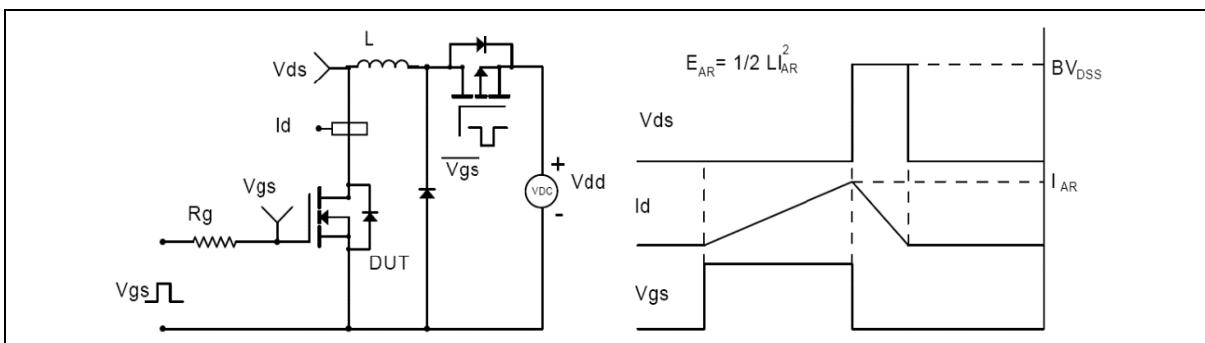


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

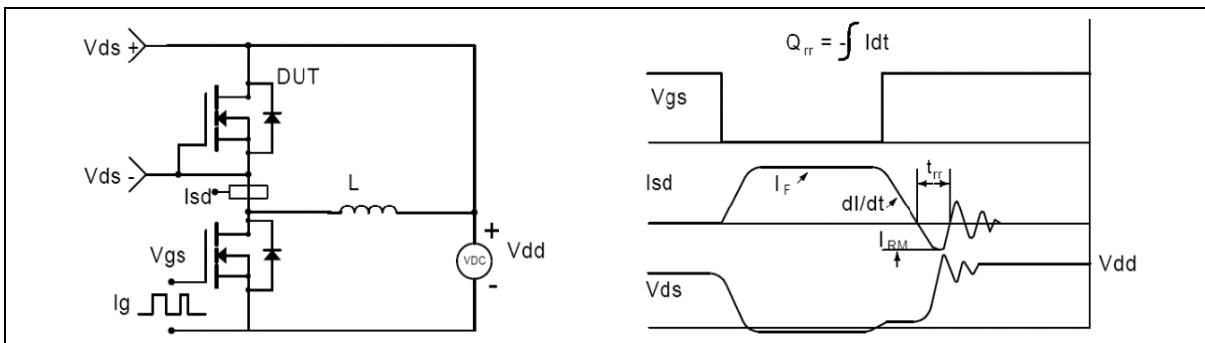
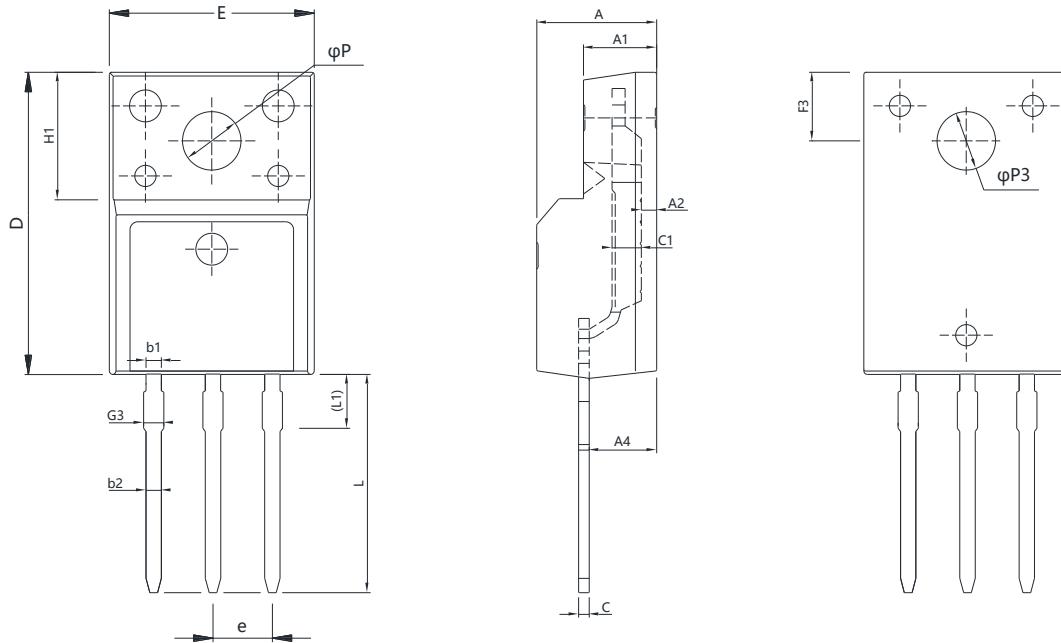


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



| Symbol | mm | | |
|--------|---------|-------|-------|
| | Min | Nom | Max |
| E | 9.96 | 10.16 | 10.36 |
| A | 4.50 | 4.70 | 4.90 |
| A1 | 2.34 | 2.54 | 2.74 |
| A2 | 0.30 | 0.45 | 0.60 |
| A4 | 2.56 | 2.76 | 2.96 |
| c | 0.40 | 0.50 | 0.65 |
| C1 | 1.20 | 1.30 | 1.35 |
| D | 15.57 | 15.87 | 16.17 |
| H1 | 6.70REF | | |
| e | 2.54BSC | | |
| L | 12.68 | 12.98 | 13.28 |
| L1 | 2.88 | 3.03 | 3.18 |
| ΦP | 3.03 | 3.18 | 3.38 |
| ΦP3 | 3.15 | 3.45 | 3.65 |
| F3 | 3.15 | 3.30 | 3.45 |
| G3 | 1.25 | 1.35 | 1.55 |
| b1 | 1.18 | 1.28 | 1.43 |
| b2 | 0.70 | 0.80 | 0.95 |

Version 1:TO220F-P package outline dimension

Ordering Information

| Package Type | Units/Tube | Tubes/Inner Box | Units/Inner Box | Inner Boxes/Carton Box | Units/Carton Box |
|--------------|------------|-----------------|-----------------|------------------------|------------------|
| TO220F-P | 50 | 20 | 1000 | 6 | 6000 |

Product Information

| Product | Package | Pb Free | RoHS | Halogen Free |
|-------------|---------|---------|------|--------------|
| OSG55R092FF | TO220F | yes | yes | yes |

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